

IMPI 53 Registrants*last updated May 10, 2019*

Badge First Name	Badge Last Name	Badge Organization	Country
Benone	Achiriloaie	Macom Technology Solutions	USA
Kosiantyn	Achkasov	SAIREM	France
Juan	Aguilar-Garib	University of Nuevo Leon	Mexico
Andres	Angelo	Macom	Netherlands
Fatima	Arrutia Rodrguez	University of Nottingham	United Kingdom
Monika	Balk	Muegge GmbH	Germany
Klaus	Baumgaertner	Muegge GmbH	Germany
Luciano	Bellemo	Unox SpA	Italy
Henk	Berkel	Multek	China
Jean-Paul	Bernard	SAIREM	France
Eleanor	Binner	University of Nottingham	United Kingdom
Brian	Blackwell	Odyssey Technical Solutions	USA
Glenn	Blaker	PSC, Inc. / C.A. Litzler Corp.	USA
Scott	Blaker	RF Specialists Ltd	Canada
Ray	Boxman	Tel Aviv University	Israel
Fernando	Bressan	Cartigliano SpA	Italy
Graham	Brodie	The University of Melbourne	Australia
Larry	Broome	Odyssey Technical Solutions	USA
Tab	Burkman	Conagra Brands	USA
Mario	Cammarota	Unox SpA	Italy
Jose Manuel	Catala-Civera	Universitat Politecnica de Valencia	Spain
Jiajia	Chen	University of Tennessee	USA
Su-Der	Chen	National Ilan University	Taiwan
Jerome	Czajkowski	Muegge-Gerling	USA
Steven	Drucker	Droaster Laboratories LLC	USA
Greg	Durnan	Kent State University	USA
Candice	Ellison	Leidos, Nat'l Energy Technology Laboratory	USA
Ulrich	Erle	Nestle R&D	USA
Kenneth	Foster	University of Pennsylvania	USA
Wenjie	Fu	University of Electronic Science and Technology	China
Marco	Garuti	MKS	Italy
John F.	Gerling	Gerling Consulting	USA
Chuting	Gong	Shanghai Jiao Tong University	China
Hannes	Grubinger	HUBER+SUHNER AG	Switzerland
Stephan	Holtrup	pinkRF	Netherlands
Christopher	Hopper	ITW	USA
Satoshi	Horikoshi	Sophia University	Japan
Rachel	Huang	Wattsine Electronics	China
Stephanie	Jarno	HUBER+SUHNER AG	Switzerland
Yang	Jiao	Shanghai Ocean University	China
Marie	Jirsa	Tyson Foods	USA
Humayan	Kabir	University of Melbourne	Australia
Mohammad	Kamarehi	MKS, ASTeX Product Group	USA
Kenneth	Kaplan	Cellencor, Inc.	USA
Jin	Kim	Maltani Corporation	South Korea
KJ	Kim	AllianceNP	South Korea

Christian	Koenen	RATIONAL	Germany
Philip	Knights	Macom	USA
Bernard	Krieger	Cober, Inc.	USA
Matthew	Krieger	Cober, Inc.	USA
Enver	Krvavac	Crescend Technologies	USA
Petra	Kumi	Worcester Polytechnic Institute	USA
Alain	Le Bail	ONIRIS	France
Patricia	Le Bail	INRA BIA	France
Boram	Lee	WAVEPIA Co., Ltd.	South Korea
Sanghun	Lee	WAVEPIA Co., Ltd.	South Korea
David	Lester	NXP Semiconductors	USA
Jan	Lindholm	Dipolar AB	Sweden
Donglei	Luan	Shanghai Ocean University	China
Jennifer	Marshall-Jenkinson	MTA-UK	United Kingdom
John	Mastela	Crescend Technologies	USA
Peter	Matthews	Mega Industries, LLC	USA
Sean	McKeown	Graphic Packaging International	USA
Thomas	Miller	ACP Inc.	USA
Tomohiko	Mitani	Kyoto University	Japan
Rasheed	Mohammed	Campbell Soup Company	USA
Robert	Mueller	Gerling Applied Engineering, Inc. (a Muegge	Germany
Pranjali	Muley	Louisiana State University	USA
Franck	Nicholls	NXP Semiconductor	USA
Molly	Poisant	IMPI	USA
Birgitta	Raaholt	Research Institute of Sweden	Sweden
Marilena	Radoiu	Radiant Technologies	Canada
Vasielos	Ramopolous	Karlsruhe Institute of Technology	Germany
Rick	Rigby	3D RF Energy Corp	USA
Walter	Rönblom	Dipolar AB	Sweden
Robert F.	Schiffmann	R.F. Schiffmann Associates	USA
Dale	Schumann	Marion Process Solutions	USA
Igor	Semenov	Leibniz Institute for Plasma Science and Technol	Germany
Alicia	Standridge	IMPI	USA
Don	Stull	Microzap	USA
Ali	Taqi	University of Nottingham	United Kingdom
Fraser	Tibbetts	Ferrite Microwave Technologies	USA
Peter	Tibbetts	Ferrite Microwave Technologies	USA
David	Vennin	SAIREM	France
Mark	Watts	Campbell Soup Company	USA
Klaus	Werner	pinkRF	Netherlands
Jerry	Wessel	Richardson Electronics	USA
Robin	Wesson	Macom	Netherlands
Roger	Williams	3D RF Energy Corp	USA
Carsten	Winnewisser	TRUMPF Hüttinger GmbH	Germany
Michael	Wolf	Smart Kitchen Summit/The Spoon	USA
Zhe	Wu	University of Electronic Science and Technol	China
Vadim	Yakovlev	Worcester Polytechnic Institute	USA
Yang	Yang	Sichuan University	China
Frank	Younce	Washington State University	USA
Hangjin	Zhang	Shanghai Jiao Tong University	China
Huacheng	Zhu	Sichuan University	China